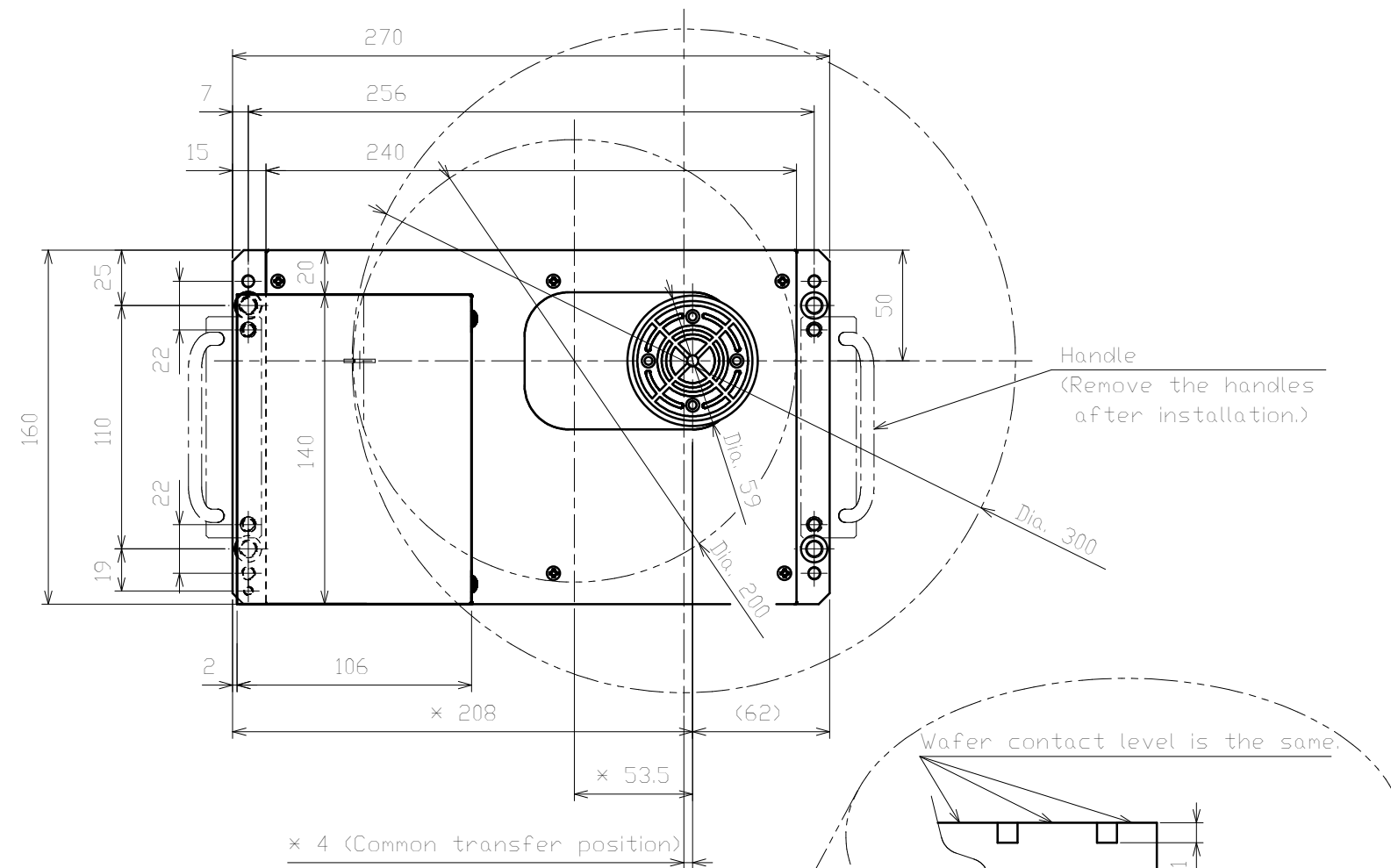
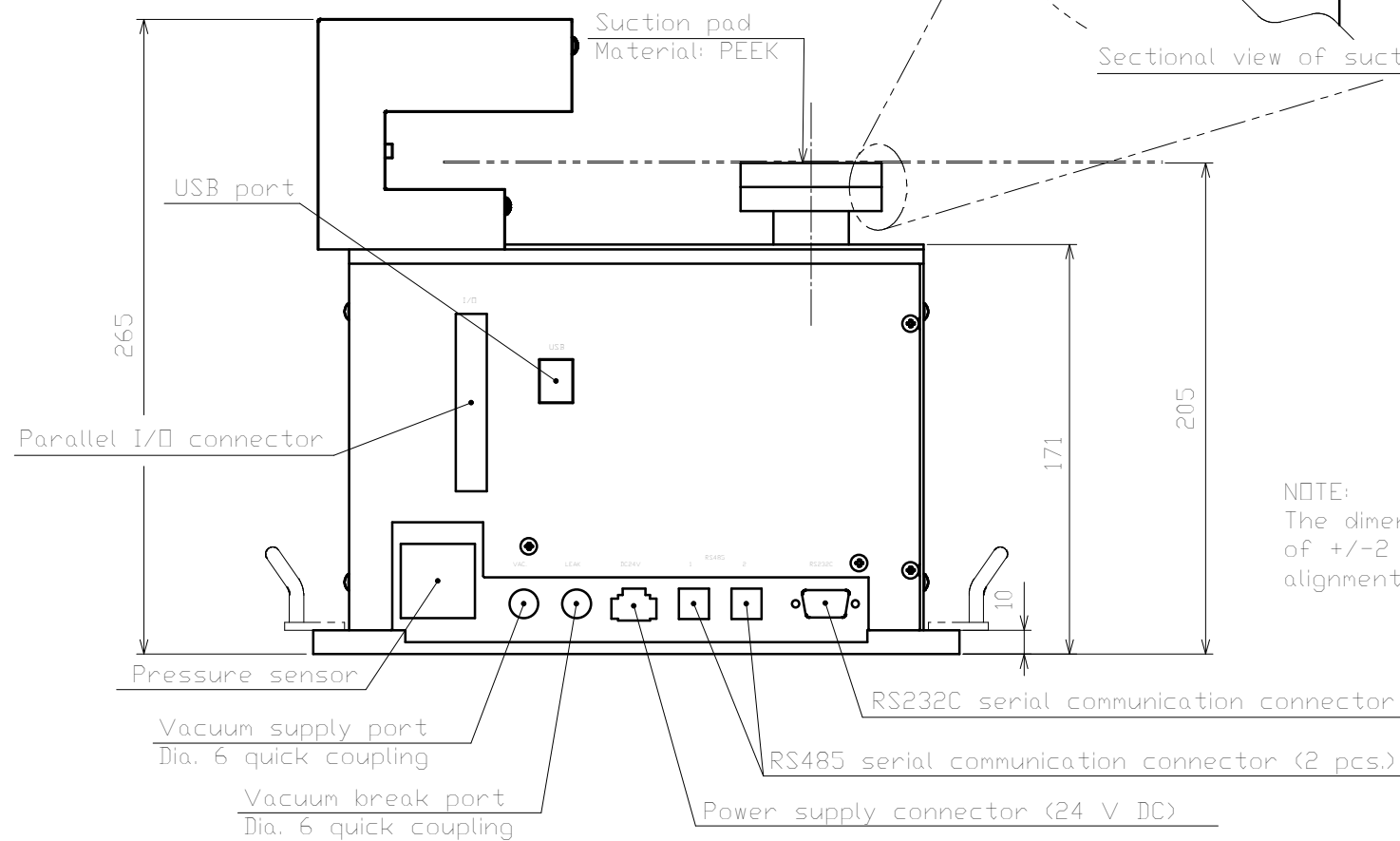




Wafer contact level is the same.

Sectional view of suction pad

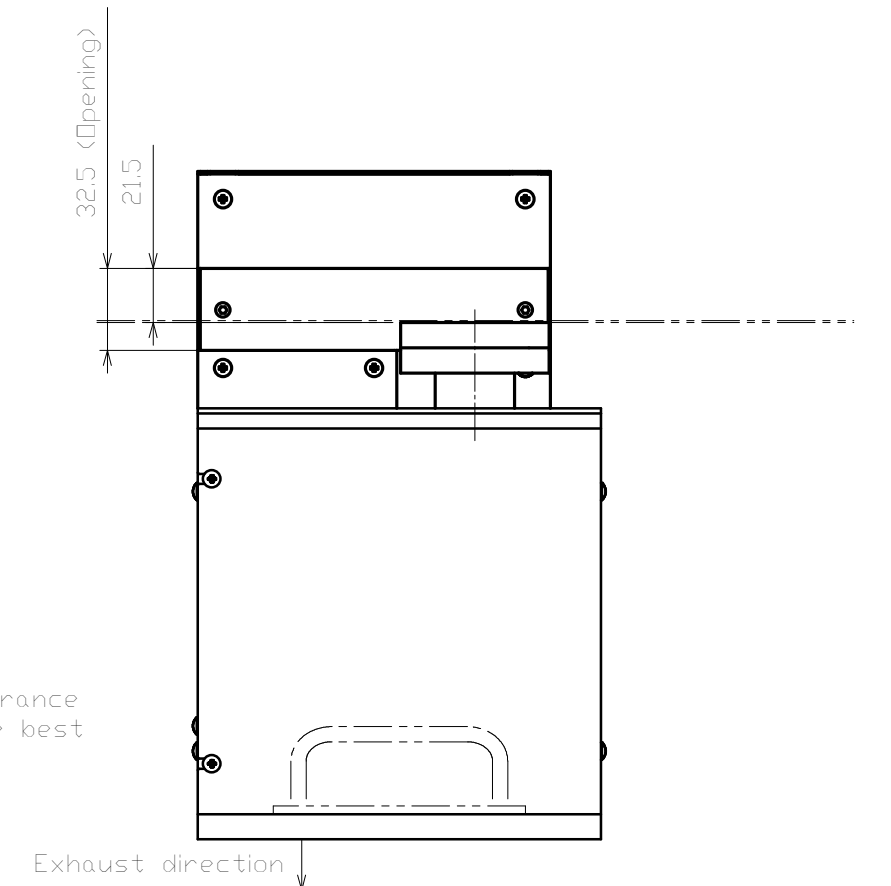


NOTE:
The dimensions "×" have a tolerance of ± 2 mm to adjust for the best alignment position.

Reference drawing

× This drawing may be revised without any advance notification.

× When designing the equipment layout based on this drawing, please confirm with JEL in advance.



Exhaust direction